RELIABILITY REPORT

FOR

MAX4661EAE+

PLASTIC ENCAPSULATED DEVICES

May 29, 2012

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Reliability Engineer

Conclusion

The MAX4661EAE+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4661/MAX4662/MAX4663 quad analog switches feature low on-resistance of 2.5 max. On-resistance is matched between switches to 0.5 max and is flat (0.5 max) over the specified signal range. Each switch can handle rail-to-rail analog signals. Off-leakage current is only 5nA max at TA = +85°C. These analog switches are ideal in low-distortion applications and are the preferred solution over mechanical relays in automatic test equipment or applications where current switching is required. They have lower power requirements, use less board space, and are more reliable than mechanical relays. The MAX4661 has four normally closed (NC) switches, and the MAX4662 has four normally open (NO) switches. The MAX4663 has two NC and two NO switches, and features guaranteed break-before-make switching. These devices operate from a single +4.5V to +36V supply or from dual ±4.5V to ±20V supplies. A separate logic supply pin guarantees TTL/CMOS-logic compatibility when operating across the entire supply voltage range.

II. Manufacturing Information

A. Description/Function:	2.5 Ohm Quad, SPST, CMOS Analog Switches
B. Process:	S5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines
F. Date of Initial Production:	July 24, 1999

III. Packaging Information

A. Package Type:	16L SSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0120 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	140°C/W
K. Single Layer Theta Jc:	34°C/W
L. Multi Layer Theta Ja:	86°C/W
M. Multi Layer Theta Jc:	33°C/W

IV. Die Information

A. Dimensions:	140 X 163 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{4.04}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 30.3 \times 10^{-9}$

$\lambda = 30.3$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S5 Process results in a FIT Rate of 0.09 @ 25C and 1.55 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot N77AAQ001B D/C 9928)

The AH45 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4661EAE+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	1	N77BAQ001B, D/C 9928

Note 1: Life Test Data may represent plastic DIP qualification lots.